

a'   
b'   
preventing board having a warp preventing board thickness substantially equal to the wiring board thickness.

SC-1  
a2  
Please add new claim 5 as follows:

--5. (NEW) A semiconductor device comprising:  
a semiconductor chip;  
a wiring board joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip; and  
a warp preventing board joined to the other surface of the semiconductor chip and composed of the same material as that of the wiring board, wherein the warp preventing board is another wiring board, another semiconductor chip electrically connected to the warp preventing board being joined to a surface, facing away from the semiconductor chip, of the warp preventing board.--

### **REMARKS**

Claims 1-5 are pending in the application. By this Amendment, claim 1 is amended and claim 5 is added.

The Office Action indicates that the title of the invention is not descriptive. The title of the invention is amended as indicated above. The amended title is now believed to be descriptive of the invention.

Claims 1 and 2 are rejected under 35 U.S.C. 102(b) as anticipated by Shirai et al. (U.S. Patent No. 6,137,687). The rejection is respectfully traversed.

Shirai et al. discloses in Fig. 5F of their patent, a structure that has a flexible board 201, a circuit chip 210 mounted on the flexible board 201, a PET sheet 212 adhered to the top surface of the circuit chip 210 by an adhesive agent.

Claim 1 is directed to a semiconductor device that includes a semiconductor chip, a wiring board and a warp preventing board. The wiring board is joined to one surface of the semiconductor chip and electrically connected to the semiconductor chip.